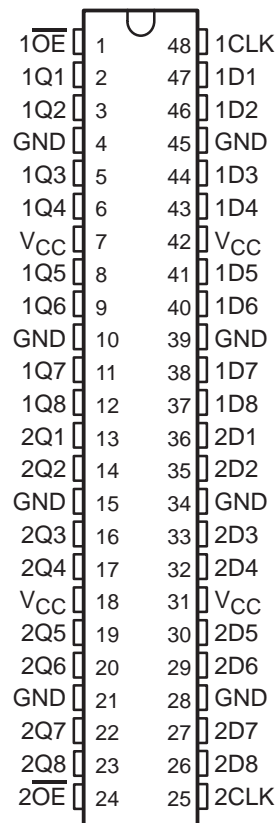# SN54ACT16374, 74ACT16374
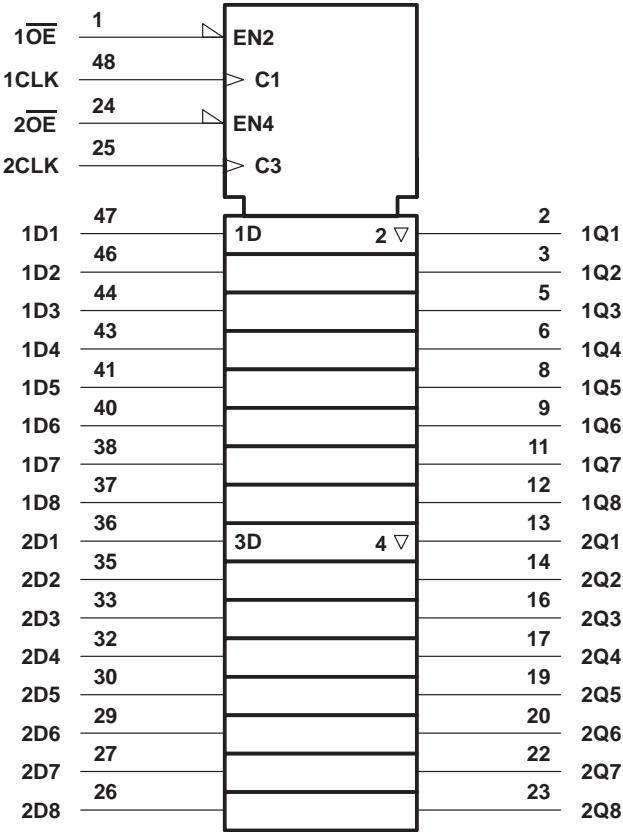# 16-BIT D-TYPE EDGE-TRIGGERED FLIP-FLOPS
WITH 3-STATE OUTPUTS

SCAS124B – MARCH 1990 – REVISED APRIL 1996

- **Members of the Texas Instruments** *Widebus*™ **Family**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Bus-Driving True Outputs**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed Center-Pin V$_{CC}$ and GND Configurations Minimize High-Speed Switching Noise**
- *EPIC*™ **(Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

SN54ACT16374 . . . WD PACKAGE
74ACT16374 . . . DL PACKAGE
(TOP VIEW)

1$\overline{OE}$	1	48	1CLK
1Q1	2	47	1D1
1Q2	3	46	1D2
GND	4	45	GND
1Q3	5	44	1D3
1Q4	6	43	1D4
V$_{CC}$	7	42	V$_{CC}$
1Q5	8	41	1D5
1Q6	9	40	1D6
GND	10	39	GND
1Q7	11	38	1D7
1Q8	12	37	1D8
2Q1	13	36	2D1
2Q2	14	35	2D2
GND	15	34	GND
2Q3	16	33	2D3
2Q4	17	32	2D4
V$_{CC}$	18	31	V$_{CC}$
2Q5	19	30	2D5
2Q6	20	29	2D6
GND	21	28	GND
2Q7	22	27	2D7
2Q8	23	26	2D8
2$\overline{OE}$	24	25	2CLK

description

The SN54ACT16374 and 74ACT16374 are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

An output-enable input ($\overline{OE}$) can be used to place the outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state provides the capability to drive bus lines in a bus-organized system without need for interface or pullup components. $\overline{OE}$ does not affect the internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16374 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit board area.

The SN54ACT16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16374 is characterized for operation from –40°C to 85°C.

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FUNCTION TABLE
(each section)

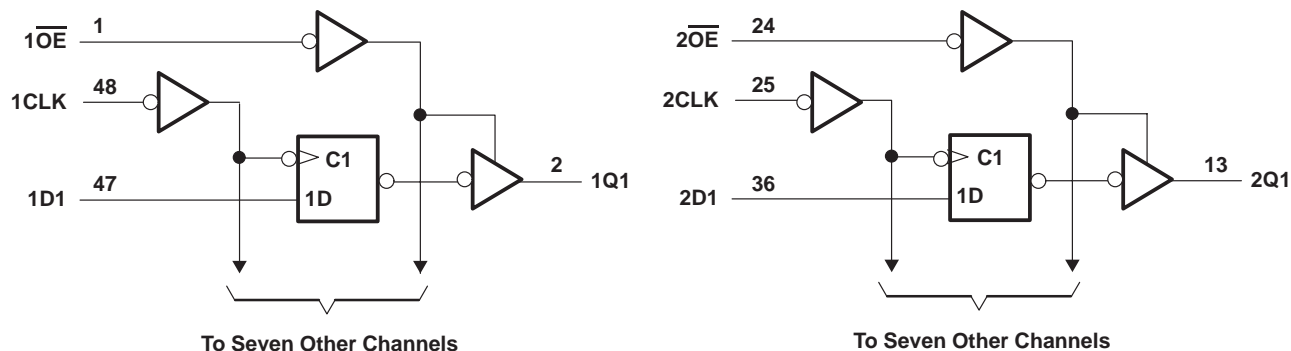| INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	H or L	X	Q_0
H	X	X	Z

logic symbol†

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1)	–0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC})	±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC})	±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±400 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		SN54ACT16374			74ACT16374			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage (see Note 4)	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current			–24			–24	mA
I_{OL}	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTES: 3. Unused inputs must be held high or low to prevent them from floating.
  4. All V_{CC} and GND pins must be connected to the proper voltage supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	$T_A = 25°C$			SN54ACT16374		74ACT16374		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$I_{OH} = -50\ \mu A$		4.5 V	4.4			4.4		4.4		V
			5.5 V	5.4			5.4		5.4		
	$I_{OH} = -24\ mA$		4.5 V	3.94			3.7		3.8		
			5.5 V	4.94			4.7		4.8		
	$I_{OH} = -50\ mA†$		5.5 V				3.85				
	$I_{OH} = -75\ mA†$		5.5 V						3.85		
V_{OL}	$I_{OL} = 50\ \mu A$		4.5 V			0.1		0.1		0.1	V
			5.5 V			0.1		0.1		0.1	
	$I_{OL} = 24\ mA$		4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
	$I_{OL} = 50\ mA†$		5.5 V					1.65			
	$I_{OL} = 75\ mA†$		5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND		5.5 V			±0.1		±1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND		5.5 V			±0.5		±10		±5	μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$		5.5 V			8		160		80	μA
$\Delta I_{CC}‡$	One input at 3.4 V, Other inputs at GND or V_{CC}		5.5 V			0.9		1		1	mA
C_i	$V_I = V_{CC}$ or GND		5 V		4.5						pF
C_o	$V_O = V_{CC}$ or GND		5 V		12						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			$T_A = 25°C$		SN54ACT16374		74ACT16374		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	65	0	65	0	65	MHz
t_w	Pulse duration	CLK low	7.5		7.5		7.5		ns
		CLK high	4.5		4.5		4.5		
t_{su}	Setup time, data before CLK↑		6.5		6.5		6.5		ns
t_h	Hold time, data after CLK↑		1		1		1		ns

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54ACT16374		74ACT16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			65			65		65		MHz
t_{PLH}	CLK	Q	5.1	8.8	10.9	5.1	13.2	5.1	12.4	ns
t_{PHL}			5.3	8.8	10.9	5.3	13.1	5.3	12.2	
t_{PZH}	$\overline{OE}$	Q	3.7	8.4	10.5	3.7	12.7	3.7	11.9	ns
t_{PZL}			4.4	9.7	11.9	4.4	14.3	4.4	13.4	
t_{PHZ}	$\overline{OE}$	Q	5.4	7.9	9.8	5.4	10.9	5.4	10.4	ns
t_{PLZ}			4.9	7.2	9.1	4.9	10.2	4.9	9.8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance per flip-flop	Outputs enabled	C_L = 50 pF, f = 1 MHz	52	pF
	Outputs disabled		38	

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

VOLTAGE WAVEFORMS

VOLTAGE WAVEFORMS

VOLTAGE WAVEFORMS

VOLTAGE WAVEFORMS
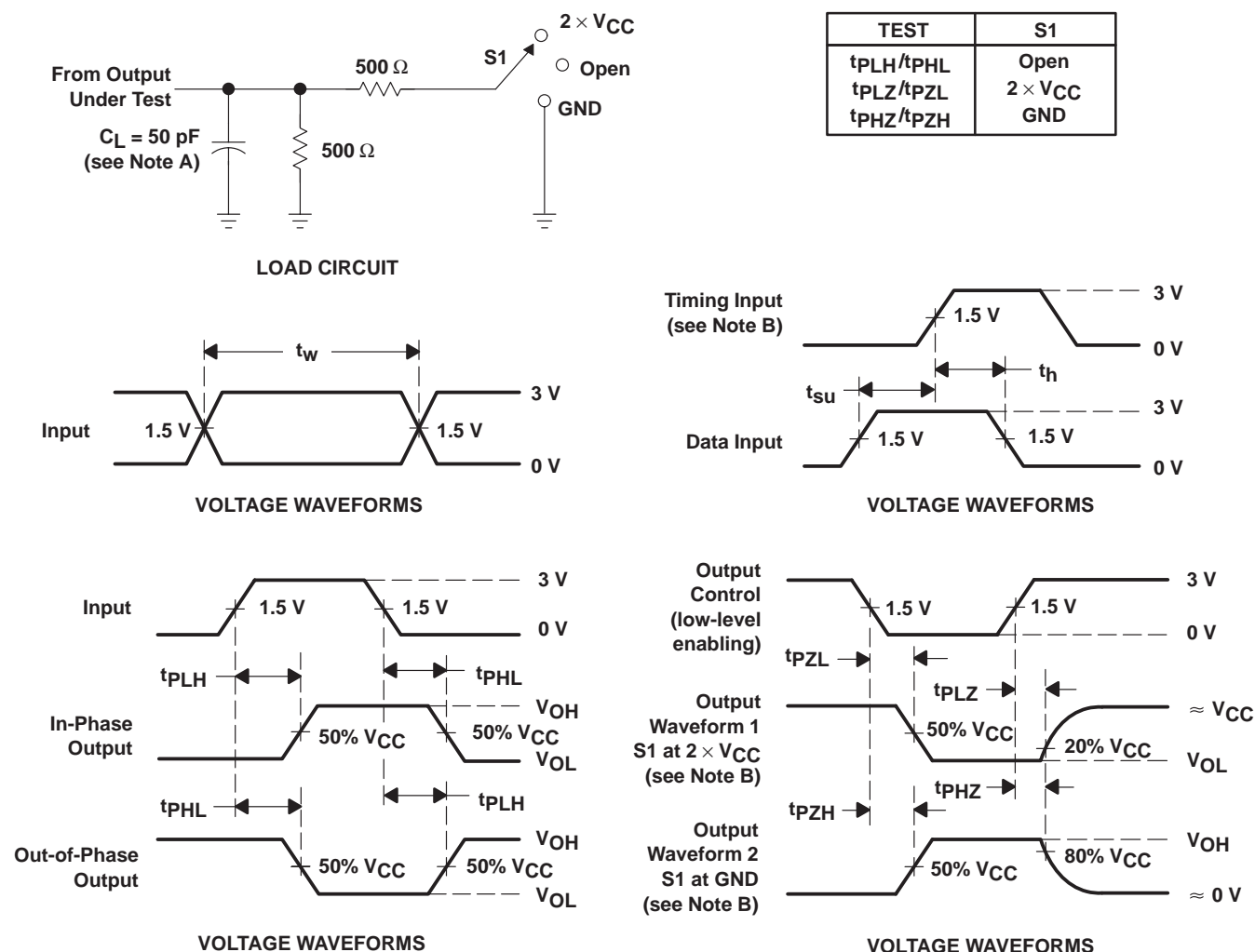
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
   Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
5962-9202501MXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC
74ACT16374DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16374DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16374DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ACT16374WD	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC

[1] The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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WD (R-GDFP-F**)   CERAMIC DUAL FLATPACK

48 LEADS SHOWN
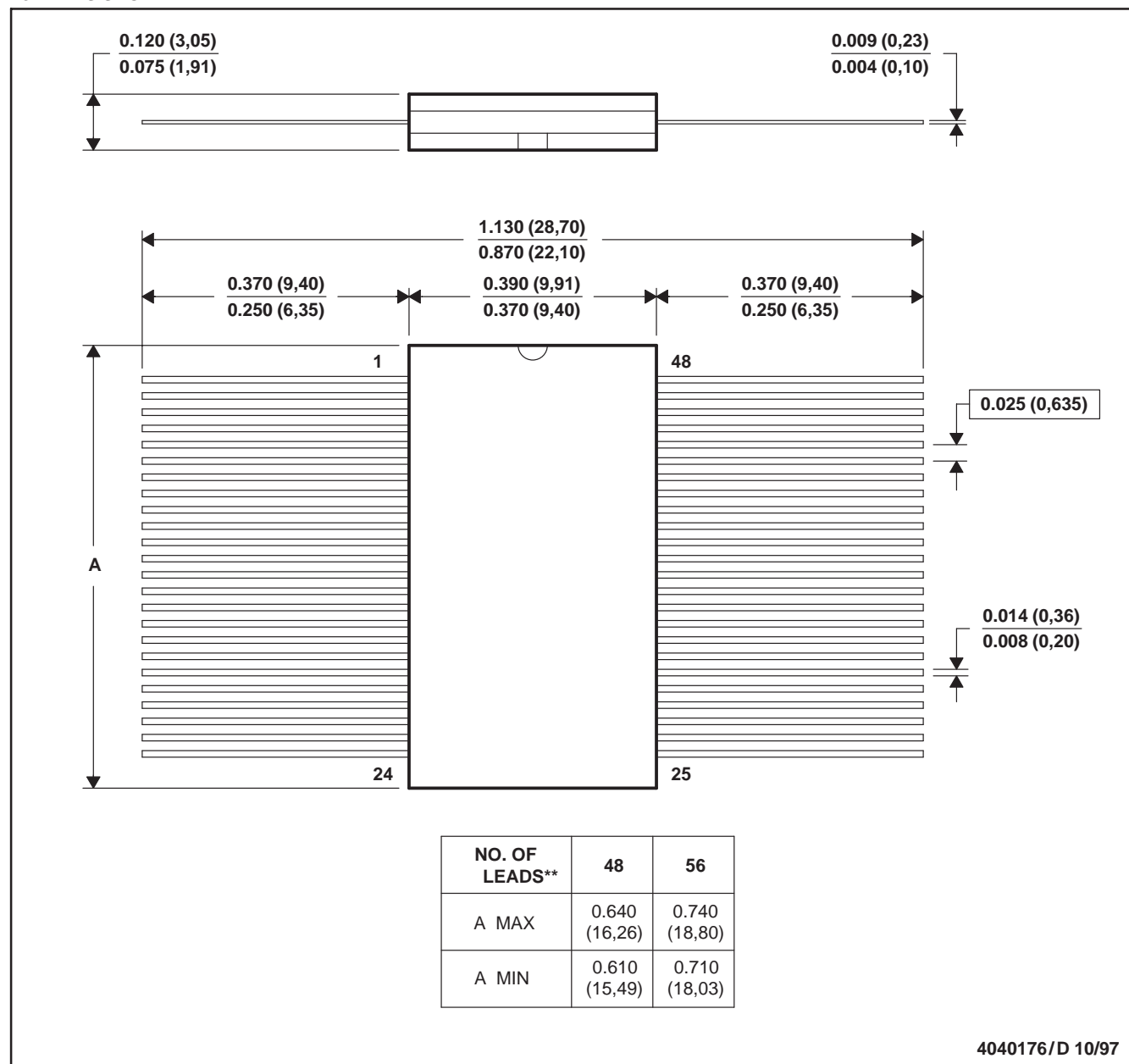
0.120 (3,05) / 0.075 (1,91)

0.009 (0,23) / 0.004 (0,10)

1.130 (28,70) / 0.870 (22,10)

0.370 (9,40) / 0.250 (6,35)

0.390 (9,91) / 0.370 (9,40)

0.370 (9,40) / 0.250 (6,35)

1   48

0.025 (0,635)

A

0.014 (0,36) / 0.008 (0,20)

24   25

NO. OF LEADS**	48	56
A MAX	0.640 (16,26)	0.740 (18,80)
A MIN	0.610 (15,49)	0.710 (18,03)

4040176 / D 10/97

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only
E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
                                            GDFP1-F56 and JEDEC MO-146AB

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DL (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

0.025 (0,635)

0.0135 (0,343) / 0.008 (0,203)

⊕ | 0.005 (0,13) | Ⓜ

48   25

0.010 (0,25) / 0.005 (0,13)

0.299 (7,59) / 0.291 (7,39)

0.420 (10,67) / 0.395 (10,03)

Gage Plane

1   24

0°–8°

0.010 (0,25)

A

0.040 (1,02) / 0.020 (0,51)

0.110 (2,79) MAX   0.008 (0,20) MIN

Seating Plane

△ | 0.004 (0,10)

PINS ** DIM	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048 / E 12/01

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D. Falls within JEDEC MO-118

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